

IV. AMENDMENTS TO THE CLAIMS

1. (Currently Amended) An adhesive tape applying method for ~~placing~~rolling an applicator ~~member~~roller in contact with a surface of adhesive tape and applying the adhesive tape to a first surface of a semiconductor wafer workpiece with a second surface of the semiconductor wafer workpiece disposed opposite the first surface being held by suction holding means, said method comprising:

a step of applying said adhesive tape to said first surface of the semiconductor wafer workpiece while the semiconductor wafer workpiece is being held at the second surface by suction via the suction holding means, while holding said adhesive tape between said applicator ~~member~~roller and said suction holding means and moving the applicator ~~member~~roller and said suction holding means relative to each other, and while vibrating the applicator roller and rolling the applicator roller across the surface of said adhesive tape.

2. (Canceled)

3. (Previously Presented) An adhesive tape applying method as defined in claim 1, wherein vibration is applied to said suction holding means for receiving and holding said semiconductor wafer workpiece.

4. (Previously Presented) An adhesive tape applying method as defined in claim 1, further comprising:

a step of applying said adhesive tape to said semiconductor wafer workpiece while heating said adhesive tape.

5. (Previously Presented) An adhesive tape applying method as defined in claim 4, wherein said adhesive tape is heated by heating the suction holding means.

6. (Canceled)

7. (Original) An adhesive tape applying method as defined in claim 1, wherein said adhesive tape is in strip form.

8. (Previously Presented) An adhesive tape applying method as defined in claim 1, wherein said adhesive tape is in label form shaped substantially to a shape of said semiconductor wafer workpiece beforehand.

9. (Previously Presented) An adhesive tape applying method as defined in claim 1, wherein said semiconductor wafer workpiece is a semiconductor wafer.

10. (Currently Amended) An adhesive tape applying apparatus for applying adhesive tape to a first surface of a semiconductor wafer workpiece, the semiconductor wafer workpiece having a second surface disposed opposite the first surface, comprising:

suction holding means for receiving said semiconductor wafer workpiece and holding the semiconductor wafer workpiece at the second surface;

tape feed means for feeding the adhesive tape toward the semiconductor wafer workpiece held by said suction holding means;

applying means for ~~placing~~ rolling an applicator ~~member~~ roller in contact with a surface of the adhesive tape and applying the adhesive tape to the first surface of the semiconductor wafer workpiece; and

first vibration generating means for vibrating said ~~applying means~~ applicator roller when the applicator roller rolls across the surface of said adhesive tape;

wherein said adhesive tape is applied to the first surface of the semiconductor wafer workpiece being held at the second surface by said suction holding means, while said adhesive tape is held between said ~~applying means~~ applicator roller and said suction holding means and the applicator roller and said

suction means are moved relative to each other, and while said adhesive tape is vibrated.

11. (Previously Presented) An adhesive tape applying apparatus as defined in claim 10, further comprising heating means for heating said suction holding means.

12. (Previously Presented) An adhesive tape applying apparatus as defined in claim 10, further comprising cutting means for cutting the adhesive tape applied to said semiconductor wafer workpiece, substantially to a shape of said semiconductor wafer workpiece.

13. (Original) An adhesive tape applying apparatus as defined in claim 10, wherein said first vibration generating means is electromagnetically operable.

14. (Original) An adhesive tape applying apparatus as defined in claim 10, wherein said first vibration generating means is constructed for rotating an eccentric weight.

15. (Previously Presented) An adhesive tape applying apparatus as defined in claim 10, further comprising second vibration generating means for vibrating said suction holding means.

16. (Original) An adhesive tape applying apparatus as defined in claim 15, wherein said second vibration generating means is electromagnetically operable.

17. (Original) An adhesive tape applying apparatus as defined in claim 15, wherein said second vibration generating means is constructed for rotating an eccentric weight.

18. (Original) An adhesive tape applying apparatus as defined in claim 10, wherein said adhesive tape is in strip form.

19. (Previously Presented) An adhesive tape applying apparatus as defined in claim 10, wherein said adhesive tape is in label form shaped substantially to a shape of said semiconductor wafer workpiece beforehand.

20. (Previously Presented) An adhesive tape applying apparatus as defined in claim 10, wherein said semiconductor wafer workpiece is a semiconductor wafer.

21. (New) An adhesive tape applying method for placing an edge member in contact with a surface of adhesive tape and applying the adhesive tape to a first surface of a semiconductor wafer workpiece with a second surface of the semiconductor wafer workpiece disposed opposite the first surface being held by suction holding means, said method comprising:

a step of applying said adhesive tape to said first surface of the semiconductor wafer workpiece while the semiconductor wafer workpiece is being held at the second surface by suction via the suction holding means, while holding said adhesive tape between said edge member and said suction holding means and moving the edge member and said suction holding means relative to each other, and while vibrating the edge member and rolling the edge member across the surface of said adhesive tape.

22. (New) An adhesive tape applying apparatus for applying adhesive tape to a first surface of a semiconductor wafer workpiece, the semiconductor wafer workpiece having a second surface disposed opposite the first surface, comprising:

suction holding means for receiving said semiconductor wafer workpiece and holding the semiconductor wafer workpiece at the second surface;

tape feed means for feeding the adhesive tape toward the semiconductor

wafer workpiece held by said suction holding means;

applying means for placing an edge member in contact with a surface of the adhesive tape and applying the adhesive tape to the first surface of the semiconductor wafer workpiece; and

first vibration generating means for vibrating said edge member when the edge member rolls across the surface of said adhesive tape;

wherein said adhesive tape is applied to the first surface of the semiconductor wafer workpiece being held at the second surface by said suction holding means, while said adhesive tape is held between said edge member and said suction holding means and the edge member and said suction means are moved relative to each other, and while said adhesive tape is vibrated.